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IDT to Demonstrate Highest Density 4K 10-bit Encoding Solution at IBC 2017

Real-time, Software-based Solution Delivers Broadcast-quality 10-bit HEVC Video Utilizing Intel Xeon E3 Processor

SAN JOSE, CALIFORNIA--(Marketwired - Sept. 6, 2017) - Integrated Device Technology, Inc. (IDT) (NASDAQ:IDTI) today announced the latest version of its R22 HEVC 10-bit software encoder. Offering high video quality, high density and low operating expense (OPEX), IDT's proprietary technology runs on the power-efficient Intel Xeon Processor E3 v5 family with integrated Intel(R) Iris(TM) Pro graphics, to provide real-time, software-based video encoding of HEVC 10-bit HDR up to 4Kp60.

"To meet the technical challenges brought on by today's new content creation, delivery, and distribution models, media and entertainment firms find themselves virtualizing nearly every function and service within their network. These virtualized video workloads can reduce time to market, cost of ownership, and delivery risk, while unlocking new revenue opportunities powered by analytics and service orchestration (automated service delivery). Hewlett Packard Enterprise provides the right technology to enable hybrid cloud infrastructure, empower the intelligent edge, and leverage services and solutions from best of breed partners, like IDT, to simplify the transformation of our customers' video services delivery," said Dan Lakey, Media and Entertainment Domain Executive, Hewlett Packard Enterprise.

"We are excited to be highlighting our latest software-based encoding solution at the upcoming IBC show in Amsterdam in partnership with Intel and HPE," said David Ko, Sr. Product Marketing Manager of Video Products at IDT, Inc. "The industry-leading density of our latest software encoding solution, in combination with our own HEVC algorithm, allows video service providers to deliver the broadcast-quality video that they need to remain competitive in a rapidly changing environment."

Utilizing Intel Xeon E3 processor, IDT's latest HEVC compression solution addresses many of the problems operators and vendors face when trying to support HEVC. With high algorithmic complexity, HEVC requires high processing power for encoding or transcoding, increasing both the cost of equipment capable of supporting this technology, as well as the cost of deployment and operation compared to previous compression technologies due to higher power and space requirements. The advanced Intel Xeon E3 technology, in combination with IDT's own proprietary HEVC algorithm, addresses these issues through lower power consumption and lower cost. IDT's algorithm takes advantage of GPU optimization to offer the highest video quality.

To see a demonstration of IDT's latest HEVC Intel Xeon E3 implementation, in partnership with Hewlett Packard Enterprise (HPE), please visit Intel's stand B65 in Hall 5 at IBC 2017, September 14-18 in Amsterdam. To schedule a meeting with IDT executives at the show, please contact Ian.Jefferson@idt.com.

About IDT

Integrated Device Technology, Inc. develops system-level solutions that optimize its customers' applications. IDT's market-leading products in RF, high performance timing, memory interface, real-time interconnect, optical interconnect, wireless power and smart sensors are among the company's broad array of complete mixed-signal solutions for the communications, computing, consumer, automotive and industrial segments. Headquartered in San Jose, Calif., IDT has design, manufacturing, sales facilities and distribution partners throughout the world. IDT stock is traded on the NASDAQ Global Select Stock Market(R) under the symbol "IDTI." Additional information about IDT can be found at www.IDT.com. Follow IDT on Facebook, LinkedIn, Twitter, and YouTube.

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